

Bump-bonds

Area: $\sim 2\text{ cm} \times 2\text{ cm}$

Coolant
Inlet/Outlet

Sensor $\sim 200\text{ }\mu\text{m}$ thick

FE chip $\sim 150\text{ }\mu\text{m}$ thick

Area: $\sim 2\text{ cm} \times 2\text{ cm}$

FE chip backside
 $\sim 300 - 700\text{ }\mu\text{m}$ thick

Area: $>\sim 2\text{ cm} \times 2\text{ cm}$

μ -channels

CO_2 boiling
in μ -channels

